

1



MATERIAL:

INSULATOR: HIGH TEMPERATURE THERMOPLASTIC,
UL 94V-0.COLOR: BLACK LCP

CONTACT: COPPER ALLOY

PLATING:

CONTACT: PLATED 30U" NI OVERALL

PLATED AU SELECTIVE CONTACT AREA

SHELL: PLATED 30U" NI OVERALL,PAD G/F AU

ELECTRICAL:

CURRENT RATING: 0.5AMPS

VOLTAGE RATING: 5V AC/DC

AMBIENT TEMPERATURE RANGE: $-20^{\circ}\text{C}\sim+60^{\circ}\text{C}$

STORAGE TEMPERATURE RANGE: $-40^{\circ}\text{C}\sim+80^{\circ}\text{C}$

AMBIENT HUMIDITY RANGE: 95% R.H. MAX.

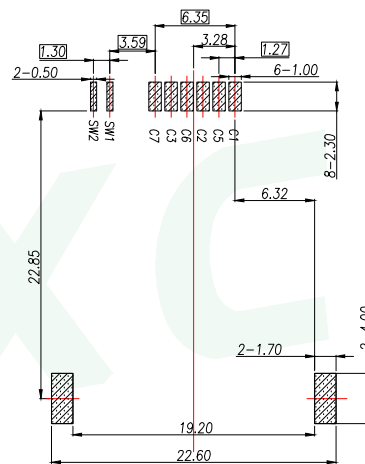
CONTACT RESISTANCE: 100MΩMAX.

INSULATION RESISTANCE: 1000MΩ

INSULATION RESISTANCE: 1000M Ω MIN./500VDC
MATING CYCLES: 5,000 INSERTIONS

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REFLOW PEAK TEMP: 260°C

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 PAD AREA

KEEP OUT AREA

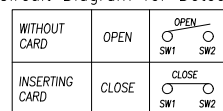
RECOMMENDED PCB LAYOUT

GENERAL TOLERANCE ± 0.05

MINI SIM CARD	
Pin No.	NAME
C1	VCC OF SIM
C2	RST OF SIM
C3	CLK OF SIM
C5	GND OF SIM
C6	VPP OF SIM
C7	I/O OF SIM
C4/C8	N/A
SW1	DETECTION SWITCH1
SW2	DETECTION SWITCH2



Circuit Diagram for Detect Switch



GENERAL TOLERANCE

DONGGUAN BAOXUN PRECISION TECHNOLOGY CO., LTD

DIM.	TOL.
X	
X.X	±0.30
X.XX	±0.25
X.XXX	±0.15
GENERAL ANGLE:	±3°

TITLE: MINI SIM CARD PUSH PUSH 6P+2P SMT无柱

DWG. NO.: *SIM103-TZ8P*

DRAWN: MAX

PART NO.: SIM103-TZ8P

CHECKED: ELLA

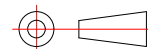
UNIT: mm	SCALE: none
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SHEET:
1 of 1

DWG. SIZE:	A4
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LAYER:	bxconn
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APPROVED: WILL

**BXCONN[®]**